

KP-2012SEC

SUPER BRIGHT ORANGE

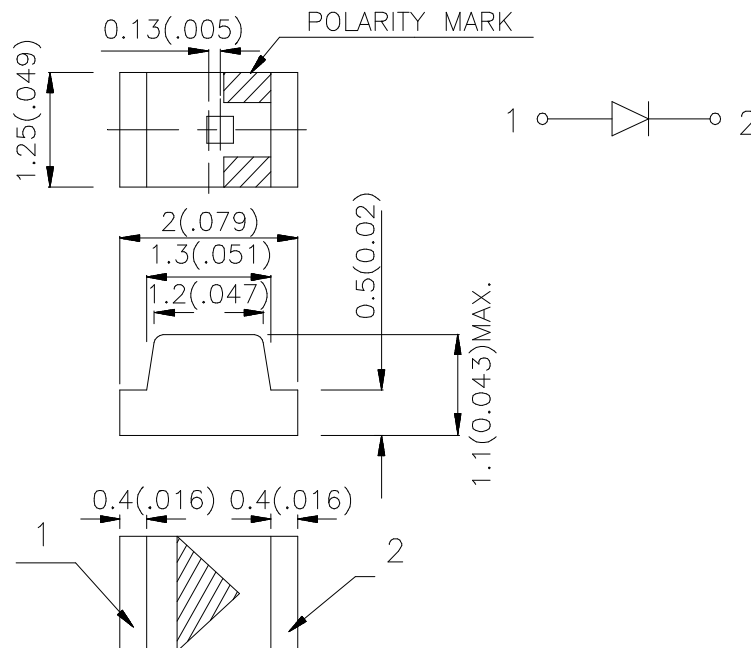
### Features

- 2.0mmx1.25mm SMT LED,1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- RoHS COMPLIANT.

### Description

The Super Bright Orange device is made with DH InGaAlP (on GaAs substrate) light emitting diode chip.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.1(0.004)$  unless otherwise noted.
3. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
KP-2012SEC	SUPER BRIGHT ORANGE (InGaAlP)	WATER CLEAR	70	200	120°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at TA=25°C

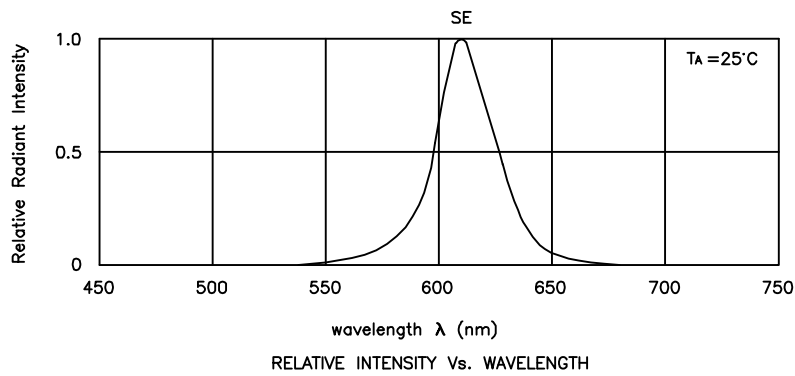
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
$\lambda_D$	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA
C	Capacitance	Super Bright Orange	30		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Orange	2.0	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR = 5V

## Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange	Units
Power dissipation	75	mW
Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

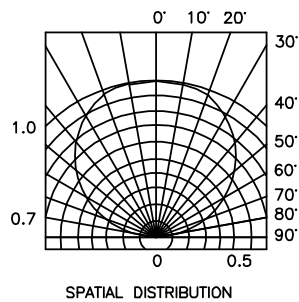
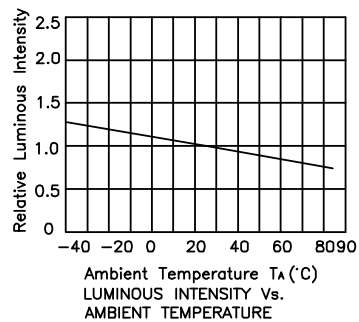
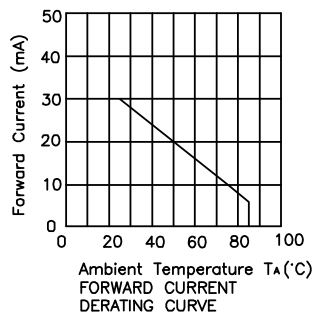
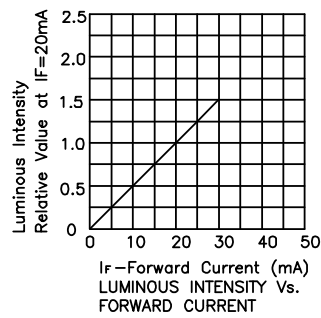
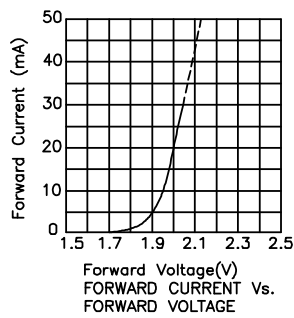
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



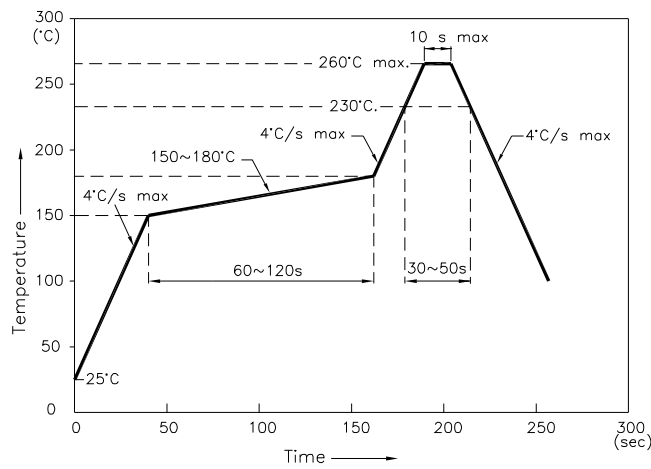
## Super Bright Orange

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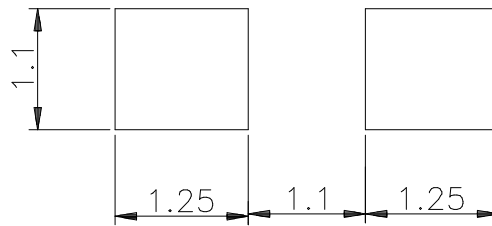
Reflow Soldering Profile For Lead-free SMT Process.



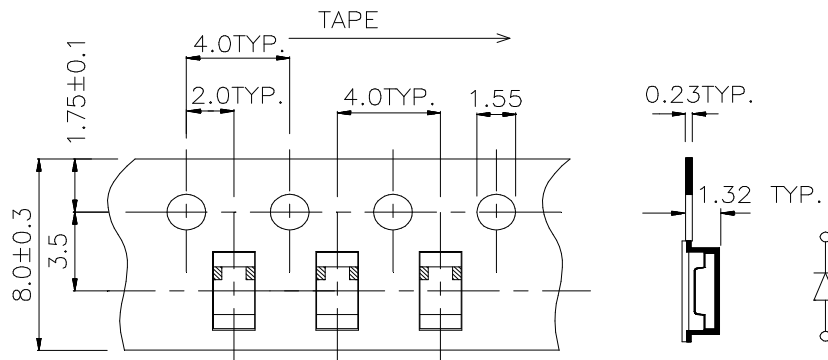
**NOTES:**

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)



**Remarks:**

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.